8-4-09

EV372459219



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

10/625,952
July 2, 2004
Ying Huang et al.
Micron Technology, Inc.
2815
J.H. Nguyen
MI22-2347
021567

Title: An Improved Method, Structure and Process Flow to Reduce Line-Line Capacitance with Low-K Material

RESPONSE TO JULY 2, 2004 OFFICE ACTION

To:

Mail Stop Amendment Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

From:

D. Brent Kenady

Tel. 509-624-4276; Fax 509-838-3424

Wells St. John P.S.

601 W. First Avenue, Suite 1300 Spokane, WA 99201-3817

Sir:

Responsive to the Office Action dated July 2, 2004, Applicant amends and remarks as follows:

AMENDMENTS

<u>Underlines</u> indicate insertions and strikeouts indicate deletions.